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 SEMI CONDUCTOR

## **150V N-Channel Enhancement Mode MOSFET**

Voltage

Current 25 A

### Features

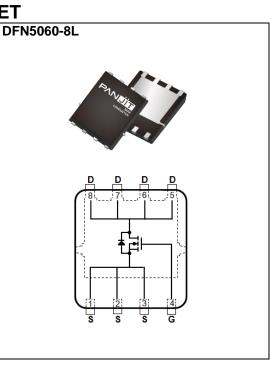
•  $R_{DS(ON)}$ ,  $V_{GS}@10V$ ,  $I_D@10A<49m\Omega$ 

150 V

- Rds(on), Vgs@7V, Id@6A<53m $\Omega$
- Excellent FOM
- Standard Level Drive
- AEC-Q101 qualified
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

### **Mechanical Data**

- Case : DFN5060-8L Package
- Terminals : Solderable per MIL-STD-750, Method 2026
- Approx. Weight : 0.08 grams



### Maximum Ratings and Thermal Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNITS	
Drain-Source Voltage		V <sub>DS</sub>	150	V	
Gate-Source Voltage		V <sub>GS</sub>	±20	v	
Continuous Drain Current <sup>(Note 3)</sup>	Tc=25°C		25		
	$T_{C}=100^{\circ}C$	I <sub>D</sub>	18	А	
Pulsed Drain Current <sup>(Note 1)</sup>	Tc=25°C	I <sub>DM</sub>	52		
Power Dissipation	Tc=25°C	Da	79	W	
	$T_{C}=100^{\circ}C$	Po	40		
Continuous Drain Current <sup>(Note 4)</sup>	T <sub>A</sub> =25°C		5.1	_	
	T <sub>A</sub> =70 <sup>°</sup> C	I <sub>D</sub>	4.3	A	
Power Dissipation	T <sub>A</sub> =25 <sup>°</sup> C	PD	3.3	W	
	T <sub>A</sub> =70 <sup>°</sup> C		2.3	VV	
Single Pulse Avalanche Current <sup>(Note 5)</sup>		las	25	А	
Single Pulse Avalanche Energy <sup>(Note 5)</sup>		Eas	55	mJ	
Operating Junction and Storage Temperature Range		T <sub>J</sub> ,T <sub>STG</sub>	-55~175	°C	
Thermal Resistance <sup>(Note 4)</sup>	Junction to Case	R <sub>θJC</sub>	1.9	°C/W	
	Junction to Ambient	R <sub>0JA</sub>	45		



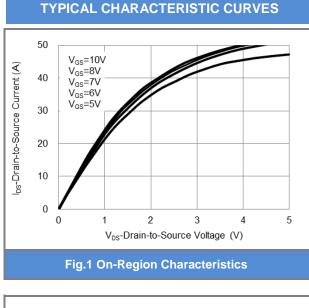
### Electrical Characteristics (TA=25°C unless otherwise noted)

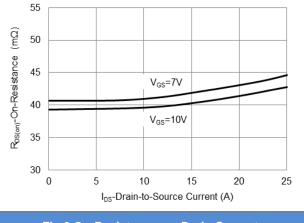
PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS	
Static	·						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	$V_{GS}$ =0V, I <sub>D</sub> =250uA	150	-	-	v	
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	2	3	4		
Drain-Source On-State Resistance		$V_{GS}$ =10V, $I_{D}$ =10A	-	39	49		
	R <sub>DS(on)</sub>	V <sub>GS</sub> =7V, I <sub>D</sub> =6A	-	41	53	mΩ	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS}$ =150V, $V_{GS}$ =0V	-	-	1	uA	
Gate-Source Leakage Current	I <sub>GSS</sub>	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	±100	nA	
Dynamic <sup>(Note 6)</sup>	-	-				-	
Total Gate Charge	Qg		-	22	29	nC	
Gate-Source Charge	Qgs	V <sub>DS</sub> =75V, I <sub>D</sub> =10A,	-	7	-		
Gate-Drain Charge	$Q_{gd}$	V <sub>GS</sub> =10V	-	6	-		
Input Capacitance	Ciss		-	1116	1450	pF	
Output Capacitance	Coss	V <sub>DS</sub> =75V, V <sub>GS</sub> =0V, f=1MHz	-	81	142		
Reverse Transfer Capacitance	Crss	I=IMHZ	-	23	-		
Gate resistance	Rg	f=1MHz	-	0.8	-	Ω	
Turn-On Delay Time	td(on)		-	8.4	-		
Turn-On Rise Time	tr	V <sub>DS</sub> =75V, I <sub>D</sub> =10A,	-	14	-		
Turn-Off Delay Time	td(off)	$V_{GS}=10V, R_G=3\Omega$	-	17	-	ns	
Turn-Off Fall Time	tf		-	11	-		
Drain-Source Diode	-				-		
Diode Forward Current	Is	Tc=25°C	-	-	25	_	
Pulsed Diode Forward Current	I <sub>SM</sub>	10=20 C	-	-	52	A	
Diode Forward Voltage	V <sub>SD</sub>	Is=20A, V <sub>GS</sub> =0V	-	0.9	1.3	V	
Reverse Recovery Time	Trr	V <sub>DD</sub> =75V,V <sub>GS</sub> =0V	-	58	-	ns	
Reverse Recovery Charge	Qrr	Is=20A,dIs/dt=100A/us	-	90	-	nC	

NOTES :

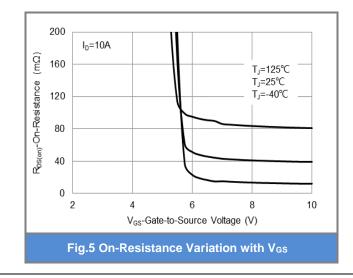
- 1. Pulse width100us, Duty cycle<2%.</td>
- 2. Essentially independent of operating temperature typical characteristics.
- 3. Chip capability with an  $R_{\theta JC}$ = 1.9°C/W.
- 4.  $R_{\theta,JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch<sup>2</sup> with 2oz.square pad of copper.
- 5. E<sub>AS</sub> is calculated based on the condition of L=1mH, I<sub>AS</sub>=10.5A, V<sub>DD</sub>=30V, V<sub>GS</sub>=10V. 100% test at L=0.1mH, I<sub>AS</sub>=25A in production.
- 6. Guaranteed by design, not subject to production testing.

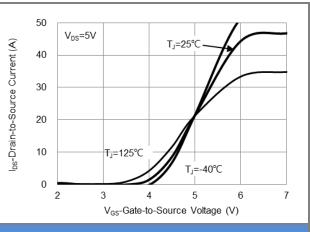












#### **Fig.2 Transfer Characteristics**

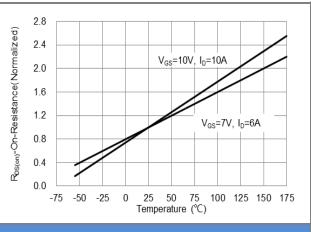
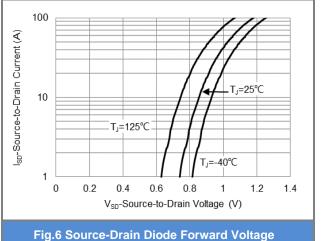
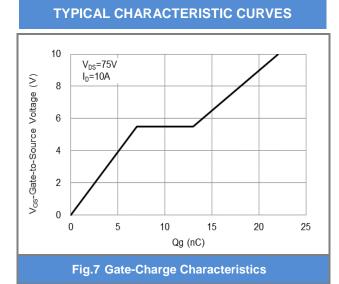


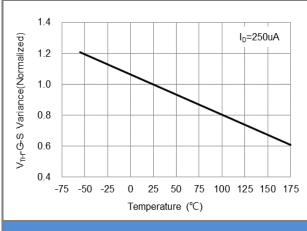
Fig.4 On-Resistance vs. Junction temperature



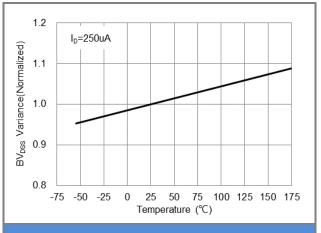
### PJQ5594-AU-REV.00













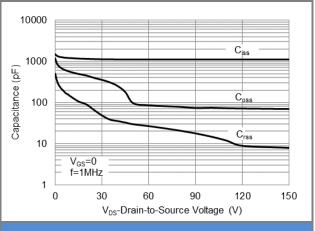
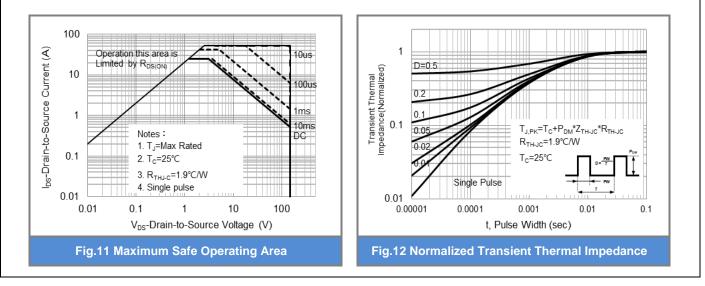


Fig.10 Capacitance vs. Drain-Source Voltage

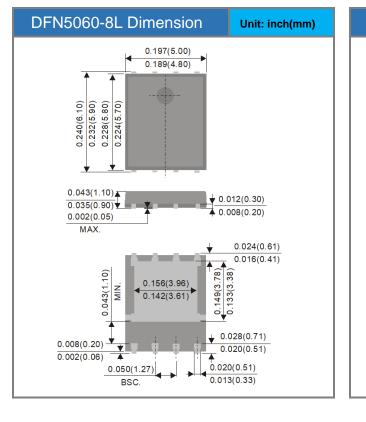


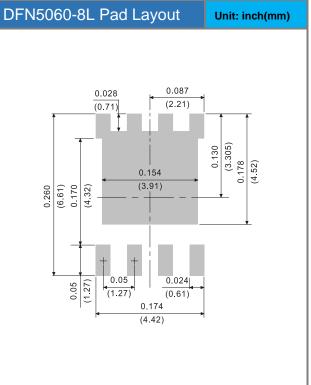


### **Product and Packing Information**

Part No.	Package Type	Packing Type	Marking	
PJQ5594-AU	DFN5060-8L	3K pcs / 13" reel	Q5594	

## Packaging Information & Mounting Pad Layout







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